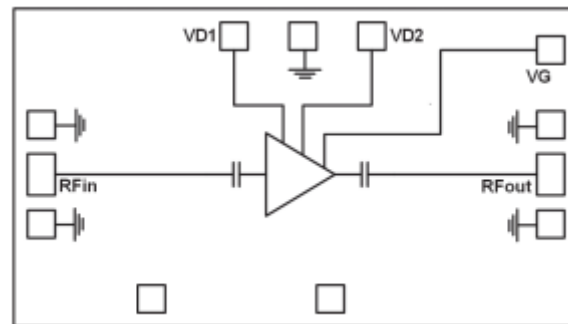


Features

- Frequency: 38-48GHz
- Gain: 25dB
- P1dB: +15dBm
- Power supply: +5.0V@90mA
- Die Size: 1500 x 850 μ m

Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

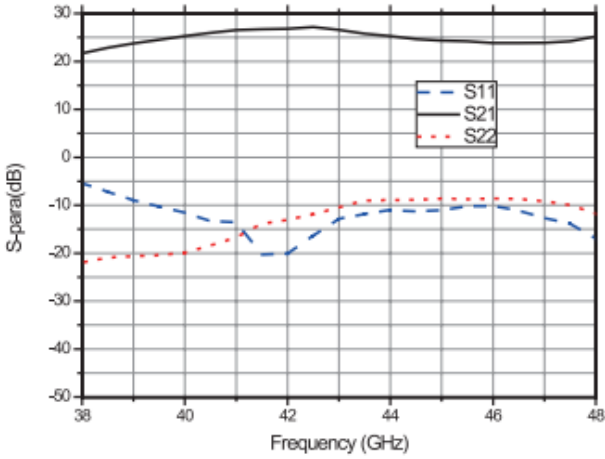
Functional Block Diagram

Electrical Specifications

TA = +25°C, VD1=VD2= +5V, VG = -0.75V

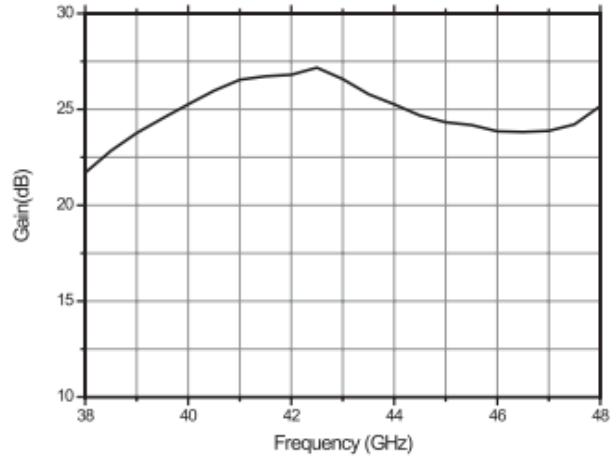
Parameters	Min.	Typ.	Max.	Units
Frequency	38-48			GHz
Gain		25		dB
P1dB		15		dBm
Input Return Loss		10		dB
Output Return Loss		10		dB
Operating Current		90		mA



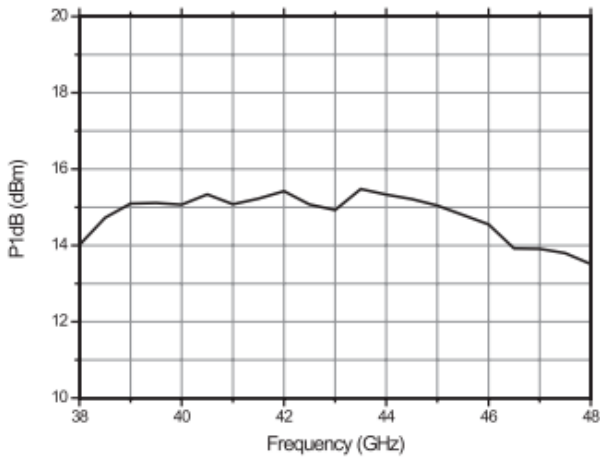
S-para vs. Frequency



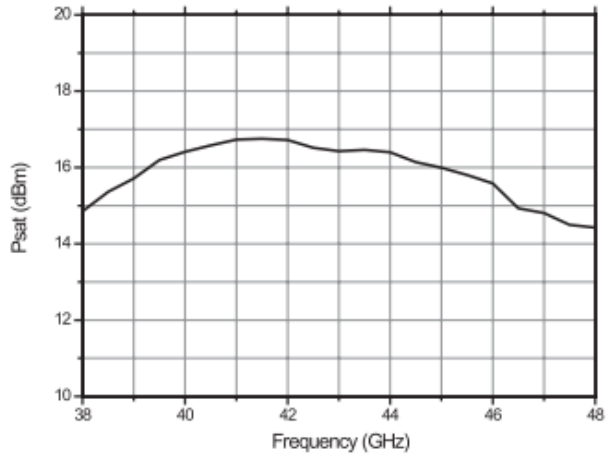
Gain vs. Frequency



P-1dB vs. Frequency

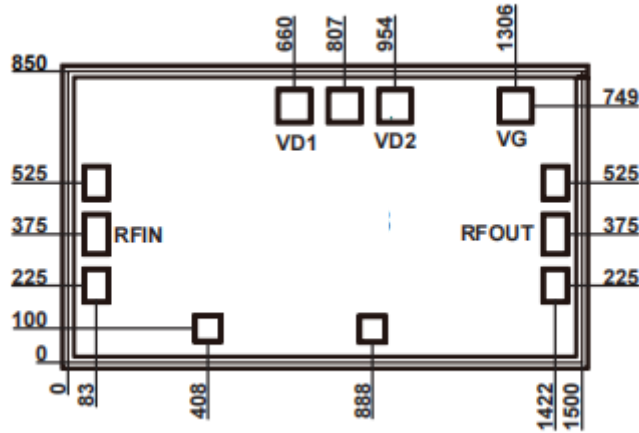


Psat vs. Frequency

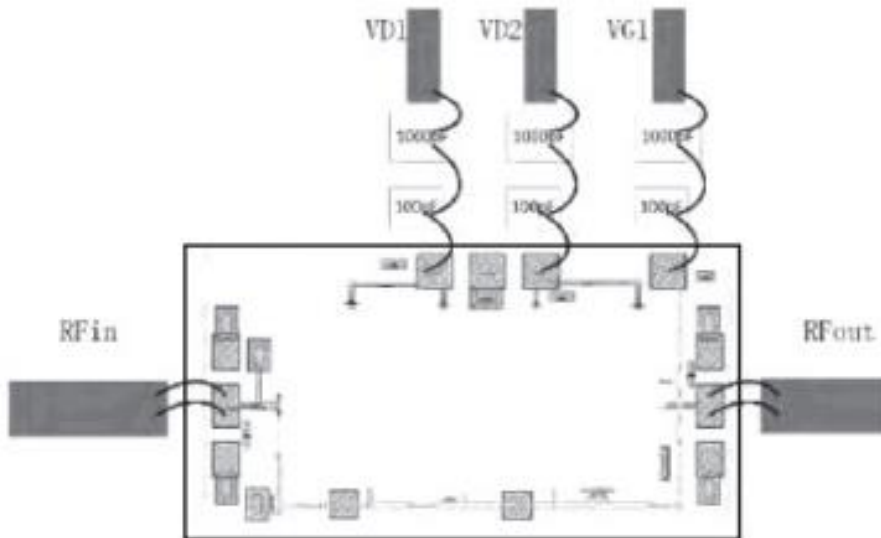




Outline Drawing: All Dimensions in um



Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm²
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads